

### Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

### Applications

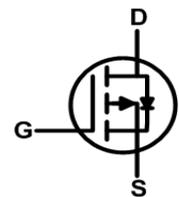
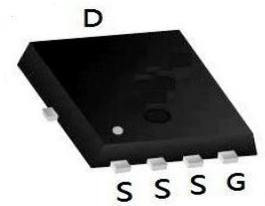
- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

### Product Summary



BVDSS	RDSON	ID
- 60V	10 mΩ	-60A

### PDFN5060-8L Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	-60	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	-38	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-240	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	337	mJ
$I_{AS}$	Avalanche Current	---	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	114	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	60	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.1	$^\circ C/W$

### Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

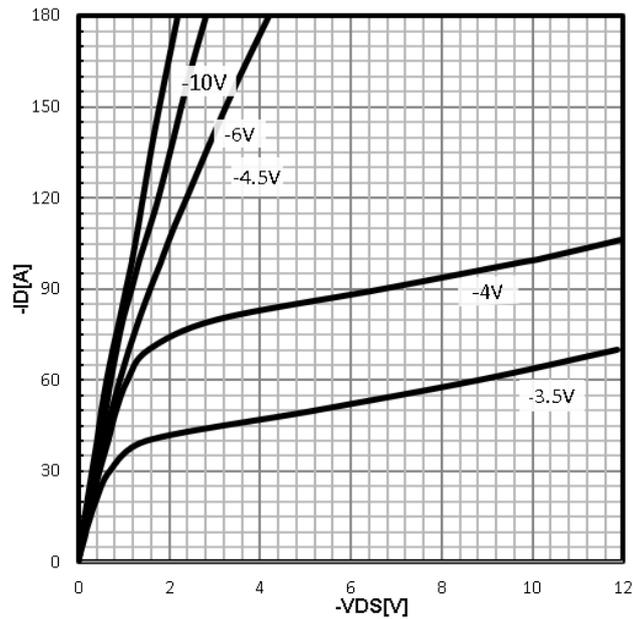
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=-1\text{mA}$	---	---	---	V/ $^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-20A$	---	10	13	m $\Omega$
		$V_{GS}=-4.5V, I_D=-10A$	---	12	16	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.3	-1.8	-2.3	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	mV/ $^{\circ}\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-60V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=-60V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5V, I_D=-3A$	---	---	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	12.5	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-30V, V_{GS}=-10V, I_D=-10A$	---	38	---	nC
$Q_{gs}$	Gate-Source Charge		---	6.9	---	
$Q_{gd}$	Gate-Drain Charge		---	4.98	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-30V, V_{GS}=-10V,$ $R_G=3\Omega, I_D=-10A$ $R_L=3\Omega$	---	20	---	ns
$T_r$	Rise Time		---	25	---	
$T_{d(off)}$	Turn-Off Delay Time		---	60	---	
$T_f$	Fall Time		---	30	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-30V, V_{GS}=0V, f=1\text{MHz}$	---	2630	---	pF
$C_{oss}$	Output Capacitance		---	484	---	
$C_{rss}$	Reverse Transfer Capacitance		---	9.4	---	

### Diode Characteristics

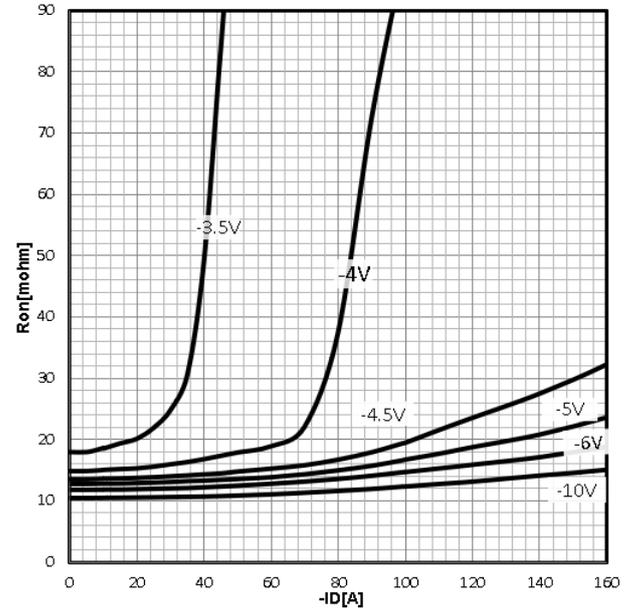
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	-60	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-5A, T_J=25^{\circ}\text{C}$	---	---	-1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=-10A, di/dt=100A/\mu s,$	---	50	---	nS
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^{\circ}\text{C}$	---	80	---	nC

### Characteristics Curve:

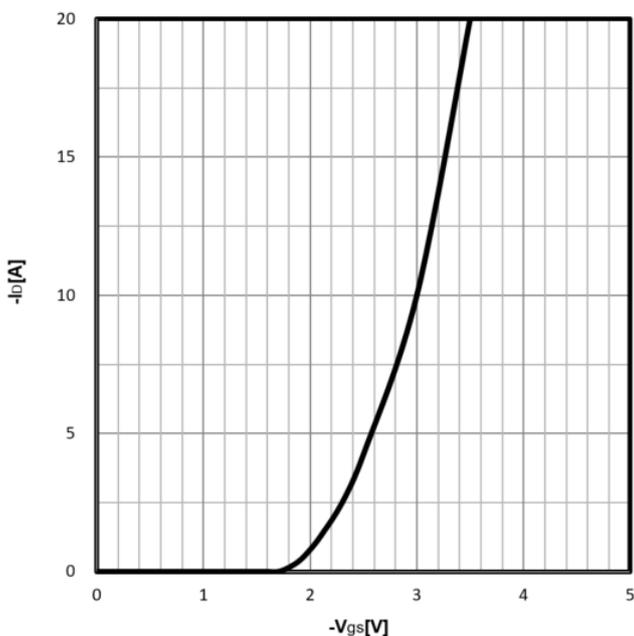
**Typ. output characteristics**  
 $-I_D = f(-V_{DS})$



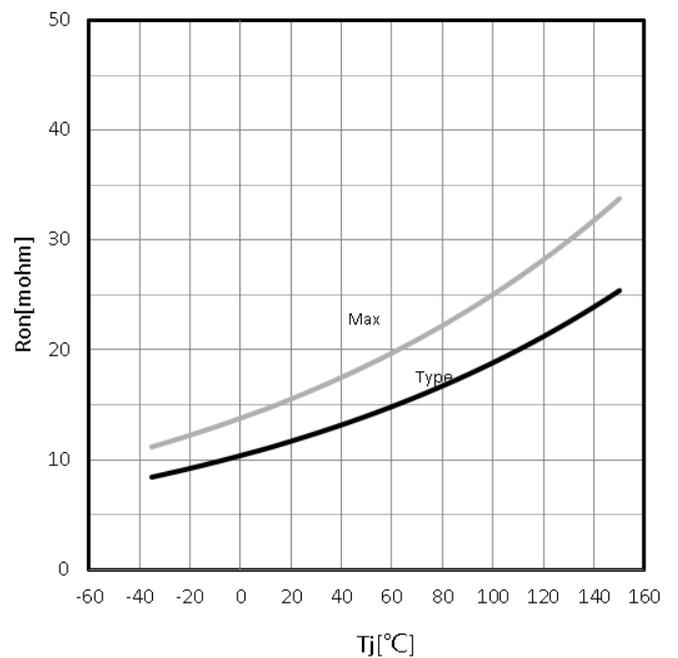
**Typ. drain-source on resistance**  
 $R_{DS(on)} = f(-I_D)$



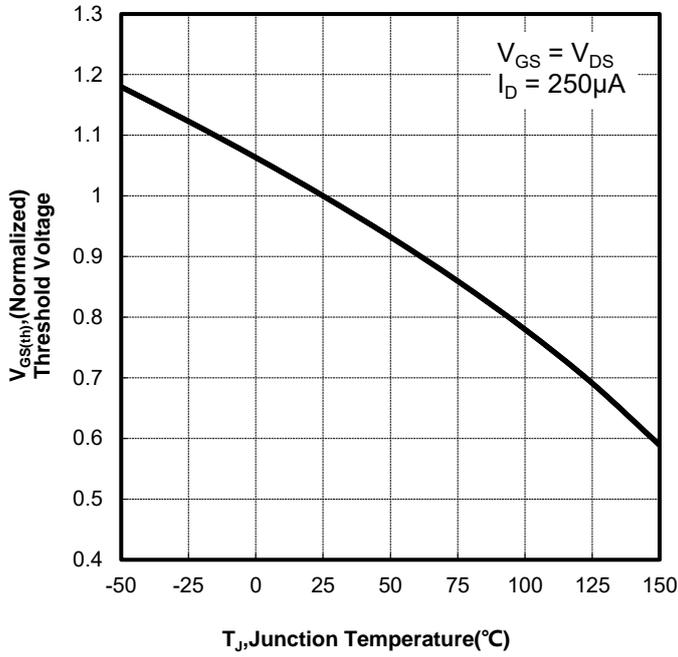
**Typ. transfer characteristics**  
 $-I_D = f(-V_{GS})$



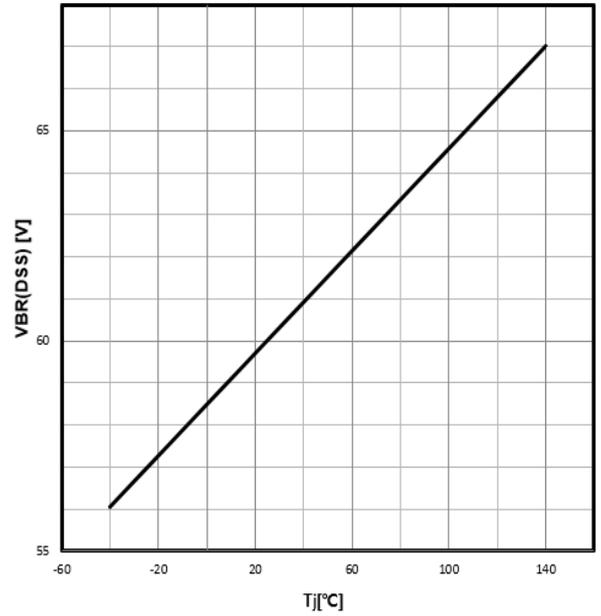
**Drain-source on-state resistance**  
 $R_{DS(on)} = f(T_j); I_D = -20A; V_{GS} = -10V$



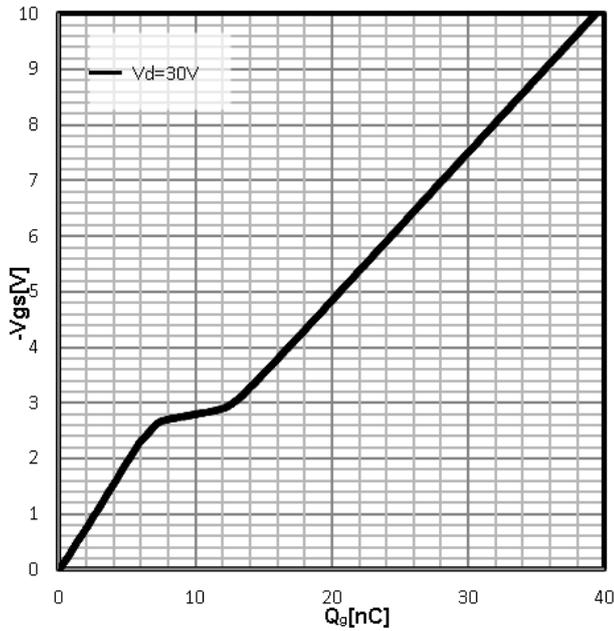
**Gate Threshold Voltage**  
 $-V_{TH}=f(T_j); I_D=-250\mu A$



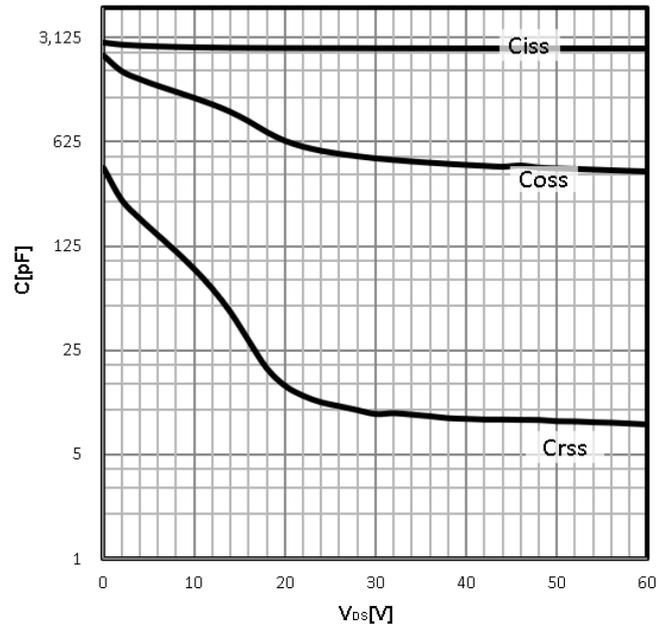
**Drain-source breakdown voltage**  
 $-V_{BR(DSS)}=f(T_j); I_D=-250\mu A$



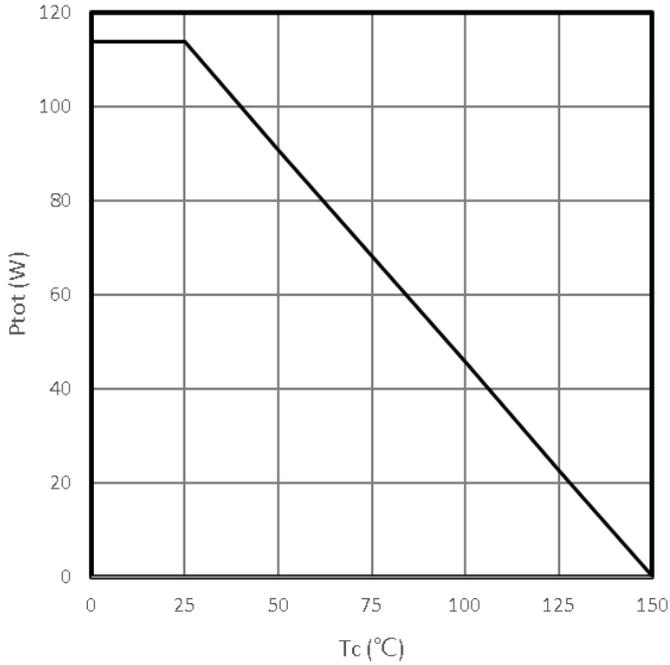
**Typ. gate charge**  
 $V_{GS}=f(Q_{gate}); I_D=-10A$



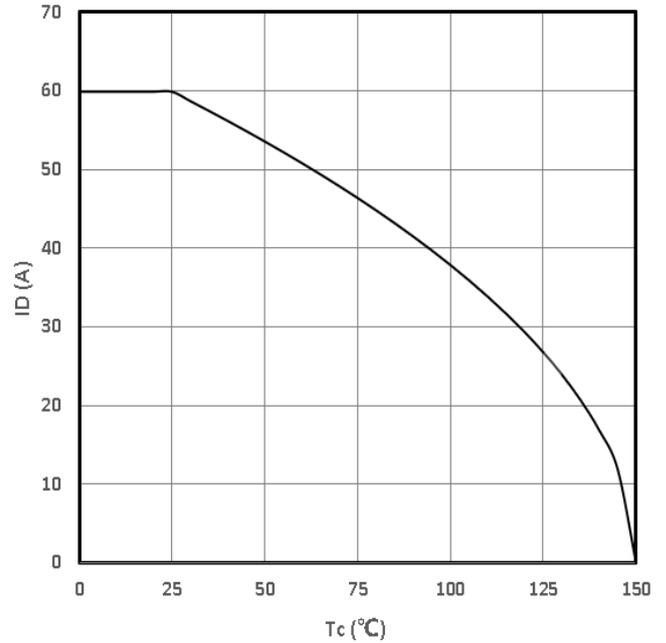
**Typ. Capacitances**  
 $C=f(-V_{DS}); V_{GS}=0V; f=1MHz$



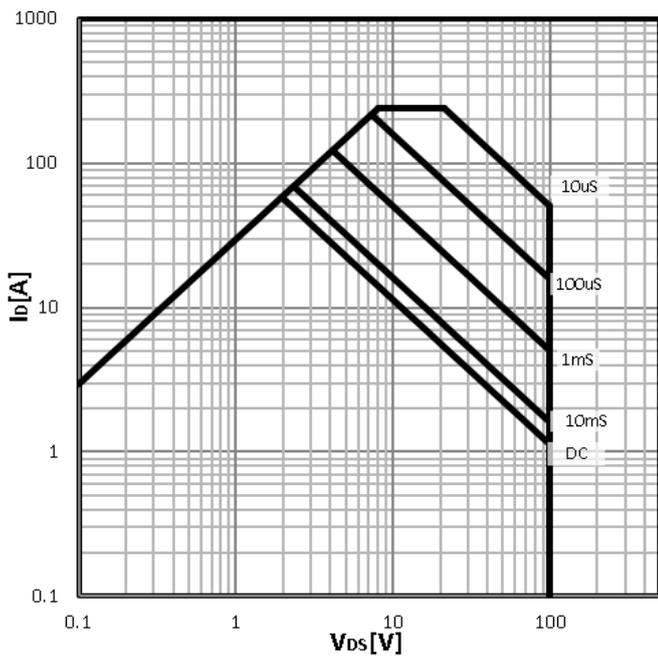
**Power Dissipation**  
 $P_{tot}=f(T_C)$



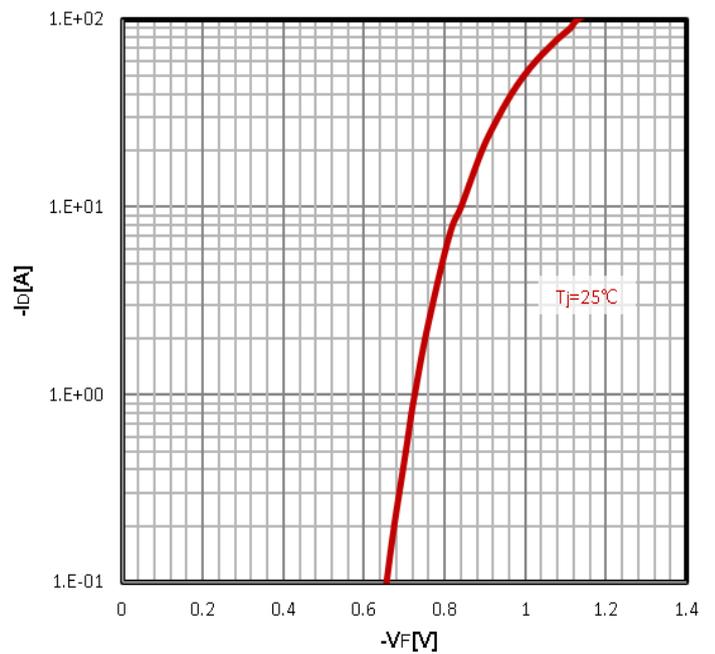
**Maximum Drain Current**  
 $-I_D=f(T_C)$



**Safe operating area**  
 $-I_D=f(-V_{DS})$

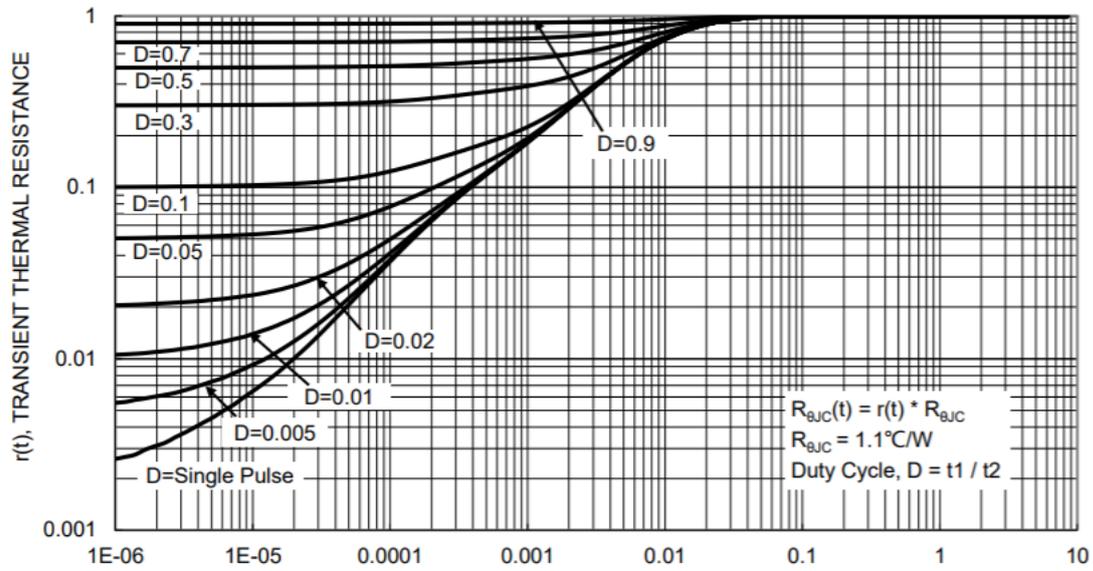


**Body Diode Forward Voltage Variation**  
 $-I_F=f(-V_{DS})$



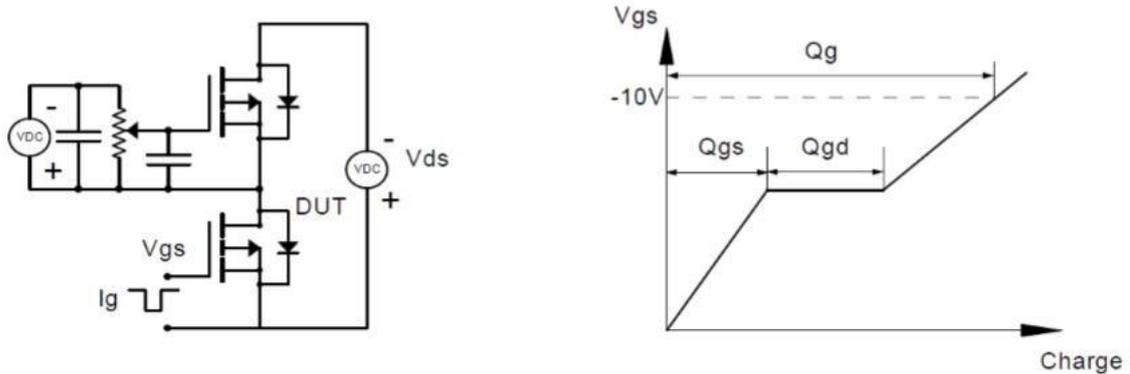
### Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$

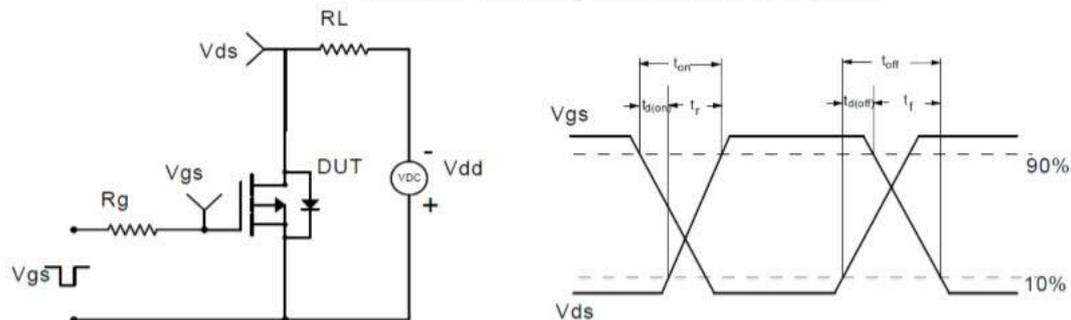


### Test Circuit and Waveform:

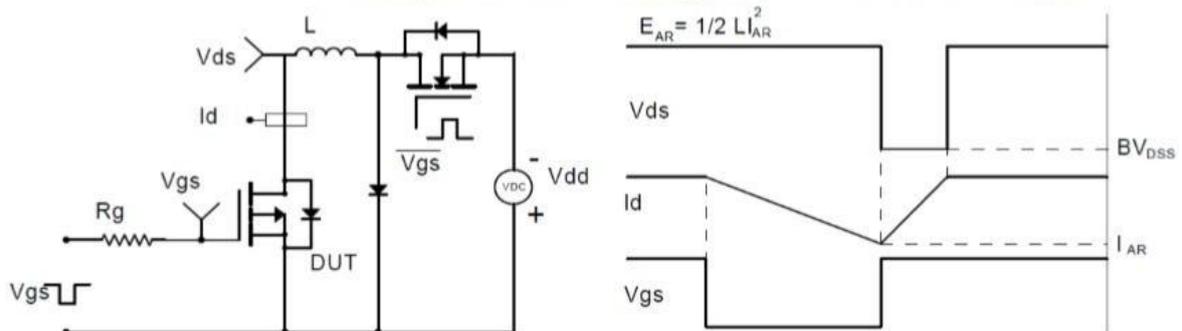
Gate Charge Test Circuit & Waveform



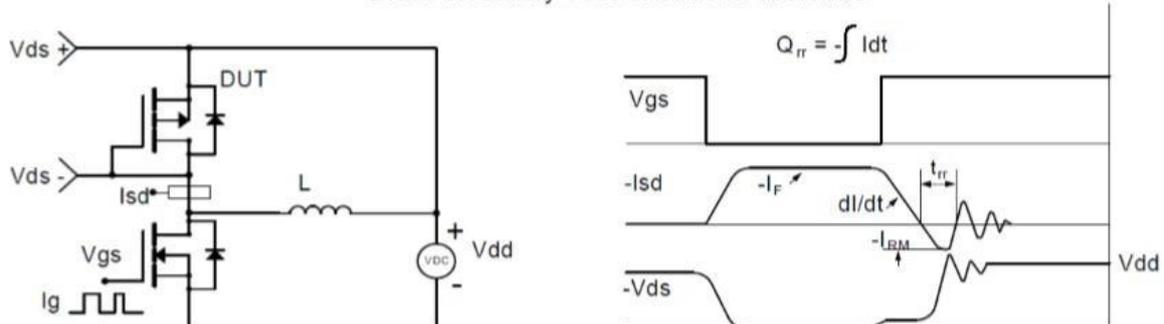
Resistive Switching Test Circuit & Waveforms



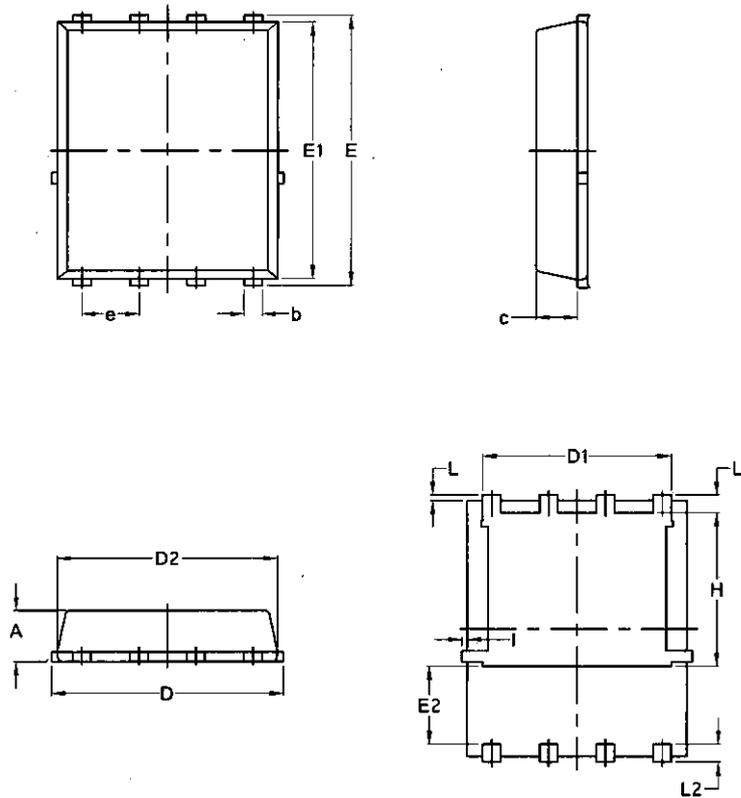
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



### Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070